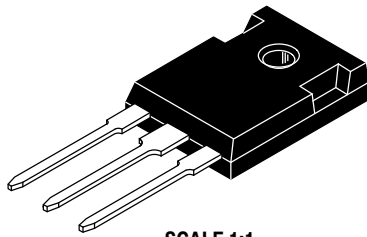


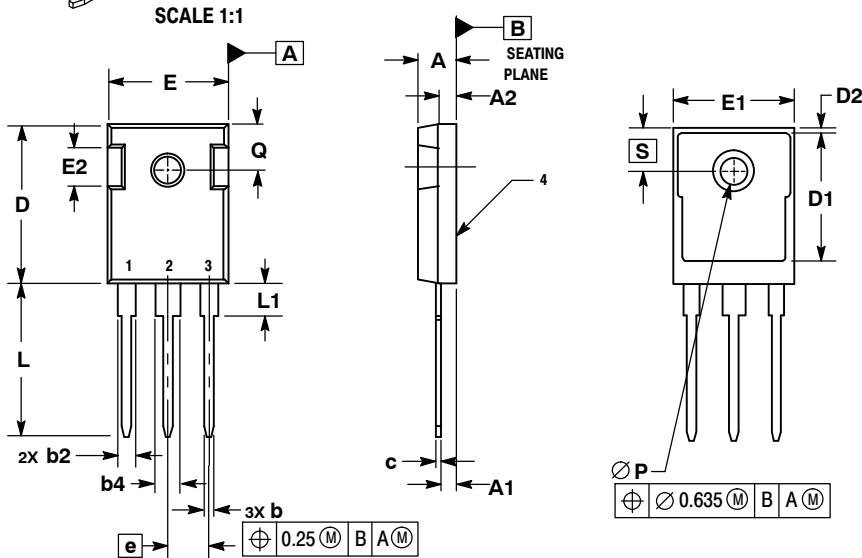
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



TO-247
CASE 340AK
ISSUE O

DATE 24 APR 2013



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.13 PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREME OF THE PLASTIC BODY.
4. SLOT REQUIRED, NOTCH MAY BE ROUNDED.
5. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS D1 AND E1.
6. LEAD FINISH UNCONTROLLED WITHIN L1.
7. $\varnothing P$ TO HAVE A MAXIMUM DRAFT ANGLE OF 1.5° TO THE TOP OF THE PART WITH A MAXIMUM DIAMETER OF 3.91.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.70	5.31	0.185	0.209
A1	2.21	2.59	0.087	0.102
A2	1.50	2.49	0.059	0.098
b	1.00	1.40	0.039	0.055
b2	1.65	2.39	0.065	0.094
b4	2.59	3.43	0.102	0.135
c	0.38	0.89	0.015	0.035
D	20.80	21.46	0.819	0.845
D1	13.08	---	0.515	---
D2	0.51	1.35	0.020	0.053
E	15.49	16.26	0.610	0.640
E1	13.46	---	0.530	---
E2	4.32	5.49	0.170	0.216
e	5.46 BSC		0.215 BSC	
L	19.81	20.32	0.780	0.800
L1	---	4.50	---	0.177
P	3.56	3.66	0.140	0.144
Q	5.38	6.20	0.212	0.244
S	6.15 BSC		0.242 BSC	

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	TO-247	PAGE 1 OF 2

